

Ordering Information (Note 4)

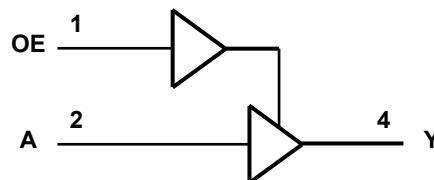
Logic Device	Function	Package	Packing
74 : Logic Prefix LVC : 1.65 to 5.5 V Logic Family 1G : One Gate	126 : 3-State Buffer OE active HIGH	W5 : SOT25 SE : SOT353 Z : SOT553 FS3 : X2-DFN0808-4 FW5 : X1-DFN1010-6 (Type B) FW4 : X2-DFN1010-6 FX4 : X2-DFN1409-6 FZ4 : X2-DFN1410-6	-7 : 7" Tape & Reel

Part Number	Package Code	Package (Notes 5 & 6)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74LVC1G126W5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm lead pitch	3000/Tape & Reel	-7
74LVC1G126SE-7	SE	SOT353	2.0mm × 2.0mm × 1.1mm 0.65mm lead pitch	3000/Tape & Reel	-7
74LVC1G126Z-7	Z	SOT553	1.6mm × 1.6 mm × 0.62mm 0.5mm lead pitch	4000/Tape & Reel	-7
74LVC1G126FS3-7	FS3	X2-DFN0808-4	0.8mm × 0.8mm × 0.35mm 0.5mm pad pitch (diamond)	5000/Tape & Reel	-7
74LVC1G126FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm × 1.0mm × 0.5mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC1G126FW4-7	FW4	X2-DFN1010-6	1.0mm × 1.0mm × 0.4mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC1G126FX4-7	FX4	X2-DFN1409-6 (Chip scale alternative)	1.4mm × 0.9mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7
74LVC1G126FZ4-7	FZ4	X2-DFN1410-6	1.4mm × 1.0mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7

Notes: 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.
 5. Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 6. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Pin Descriptions

Pin Name	Description
OE	Output Enable
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage
NC	No Connection

Logic Diagram

Function Table

Inputs		Output
OE	A	Y
H	H	H
H	L	L
L	X	Z

Absolute Maximum Ratings (Notes 7 & 8) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +6.5	V
V _I	Input Voltage Range	-0.5 to +6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to +6.5	V
V _O	Voltage Applied to Output in High or Low State	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous Output Current	±50	mA
I _{CC} , I _{GND}	Continuous Current Through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 9) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit
V _{CC}	Operating Voltage	1.65	5.5	V
	Data retention only	1.5	15	V
V _{IH}	High-Level Input Voltage	V _{CC} = 1.65V to 1.95V	0.65 × V _{CC}	V
		V _{CC} = 2.3V to 2.7V	1.7	
		V _{CC} = 3V to 3.6V	2	
		V _{CC} = 4.5V to 5.5V	0.7 × V _{CC}	
V _{IL}	Low-Level Input Voltage	V _{CC} = 1.65V to 1.95V	—	V
		V _{CC} = 2.3V to 2.7V	—	
		V _{CC} = 3V to 3.6V	—	
		V _{CC} = 4.5V to 5.5V	—	
V _I	Input Voltage	0	5.5	V
V _O	Output Voltage	0	V _{CC}	V
I _{OH}	High-Level Output Current	V _{CC} = 1.65V	—	mA
		V _{CC} = 2.3V	—	
		V _{CC} = 2.7V	—	
		V _{CC} = 3V	—	
		V _{CC} = 4.5V	—	
		V _{CC} = 1.65V	—	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	mA
		V _{CC} = 2.3V	—	
		V _{CC} = 2.7V	—	
		V _{CC} = 3V	—	
		V _{CC} = 4.5V	—	
		V _{CC} = 1.65V	—	
Δt/ΔV	Input transition Rise or Fall Rate	V _{CC} = 1.8V ± 0.15V, 2.5V ± 0.2V	—	ns/V
		V _{CC} = 3.3V ± 0.3V	—	
		V _{CC} = 5V ± 0.5V	—	
T _A	Operating Free-Air Temperature	—	-40	°C

Note: 9. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	-40°C to +85°C			-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
V_{OH}	High Level Output Voltage	$I_{OH} = -100\mu A$	1.65V to 5.5V	$V_{CC} - 0.1$	—	—	$V_{CC} - 0.1$	—	V
		$I_{OH} = -4mA$	1.65V	1.2	—	—	0.95	—	
		$I_{OH} = -8mA$	2.3V	1.9	—	—	1.7	—	
		$I_{OH} = -12mA$	2.7V	2.2	—	—	1.9	—	
		$I_{OH} = -16mA$	3V	2.4	—	—	2.2	—	
		$I_{OH} = -24mA$		2.3	—	—	2.0	—	
		$I_{OH} = -32mA$	4.5V	3.8	—	—	3.4	—	
V_{OL}	Low Level Output Voltage	$I_{OL} = 100\mu A$	1.65V to 5.5V	—	—	0.1	—	0.1	V
		$I_{OL} = 4mA$	1.65V	—	—	0.45	—	0.7	
		$I_{OL} = 8mA$	2.3V	—	—	0.3	—	0.45	
		$I_{OL} = 12mA$	2.7V	—	—	0.4	—	0.6	
		$I_{OL} = 16mA$	3V	—	—	0.4	—	0.6	
		$I_{OL} = 24mA$		—	—	0.55	—	0.8	
		$I_{OL} = 32mA$	4.5V	—	—	0.55	—	8	
I_I	Input Current	$V_I = 5.5V$ or GND	0 to 5.5V	—	± 0.1	± 5	—	± 100	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5V$	0V	—	—	± 10	—	± 200	μA
I_{OZ}	Z State Leakage Current	$V_O = 0$ to 5.5V	3.6V	—	0.1	10	—	20	μA
I_{CC}	Supply Current	$V_I = 5.5V$ or GND $I_O = 0$	5.5V	—	0.1	10	—	200	μA
ΔI_{CC}	Additional Supply Current	One input at $V_{CC} - 0.6V$ Other inputs at V_{CC} or GND	3V to 5.5V	—	—	500	—	5000	μA
C_i	Input Capacitance	$V_I = V_{CC}$ or GND	3.3V	—	5	—	—	—	pF

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 10)	—	204	—	$^\circ C/W$
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6 (Type B)		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 10)	—	52	—	$^\circ C/W$
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6 (Type B)		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 10. Test condition for each of the eight package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

Figure 1 Typical Values at $T_A = +25^\circ\text{C}$ and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V.

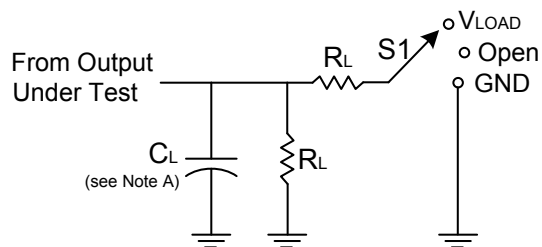
Parameter	From Input	To Output	V_{CC}	$T_A = -40^\circ\text{C to } +85^\circ\text{C}$			$T_A = -40^\circ\text{C to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	
t_{pd}	A	Y	1.8V \pm 0.15V	1.0	3.0	8.0	1.0	10.5	ns
			2.5V \pm 0.2V	0.5	2.1	5.5	0.5	7.0	
			2.7V	0.5	2.3	5.5	0.5	7.5	
			3.3V \pm 0.3V	0.5	2.0	4.5	0.5	6.0	
			5.0V \pm 0.5V	0.5	1.7	4.0	0.5	5.5	
t_{en}	OE	Y	1.8V \pm 0.15V	1.0	3.2	9.4	1.0	12.0	ns
			2.5V \pm 0.2V	0.5	2.2	6.6	0.5	8.5	
			2.7V	0.5	2.4	6.6	0.5	8.5	
			3.3V \pm 0.3V	0.5	2.1	5.3	0.5	7.0	
			5.0V \pm 0.5V	0.5	1.6	5.0	0.5	6.5	
t_{dis}	OE	Y	1.8V \pm 0.15V	1.0	4.3	9.2	1.0	12.0	ns
			2.5V \pm 0.2V	0.5	2.7	5.5	0.5	7.0	
			2.7V	0.5	3.4	5.5	0.5	7.0	
			3.3V \pm 0.3V	0.5	3.0	5.5	0.5	7.0	
			5.0V \pm 0.5V	0.5	2.2	4.2	0.5	5.5	

Operating Characteristics

$T_A = +25^\circ\text{C}$

Parameter			Test Conditions	$V_{CC} = 1.8\text{V}$	$V_{CC} = 2.5\text{V}$	$V_{CC} = 3.3\text{V}$	$V_{CC} = 5\text{V}$	Unit
				Typ	Typ	Typ	Typ	
C_{pd}	Power Dissipation Capacitance	Outputs Enabled	$f = 10\text{MHz}$	19	19	19	21	pF
		Outputs Disabled		2	2	3	4	

Parameter Measurement Information



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	Inputs		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1k Ω	0.15V
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500 Ω	0.15V
2.7V	2.7V	$\leq 2.5ns$	1.5V	6V	50pF	500 Ω	0.3V
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	6V	50pF	500 Ω	0.3V
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	50pF	500 Ω	0.3V

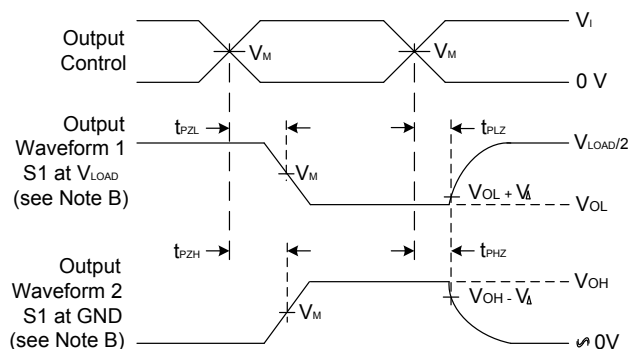
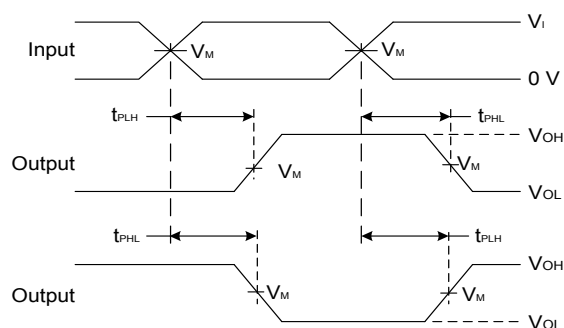
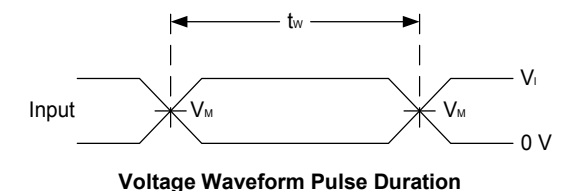
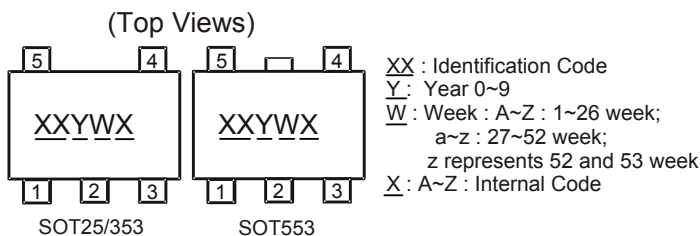


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10MHz$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - E. t_{PZL} and t_{PZH} are the same as t_{en} .
 - F. t_{PLH} and t_{PHL} are the same as t_{PD} .

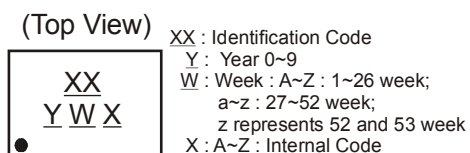
Marking Information

(1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G126W5-7	SOT25	UZ
74LVC1G126SE-7	SOT353	UZ
74LVC1G126Z-7	SOT553	UZ

(2) DFN Packages

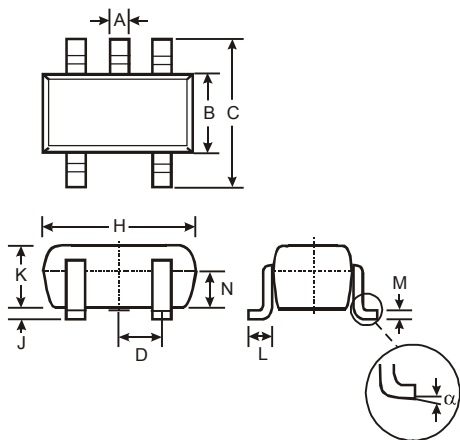


Part Number	Package	Identification Code
74LVC1G126FS3-7	X2-DFN0808-4	WZ
74LVC1G126FW5-7	X1-DFN1010-6 (Type B)	VZ
74LVC1G126FW4-7	X2-DFN1010-6	UZ
74LVC1G126FX4-7	X2-DFN1409-6	MY
74LVC1G126FZ4-7	X2-DFN1410-6	UZ

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT25

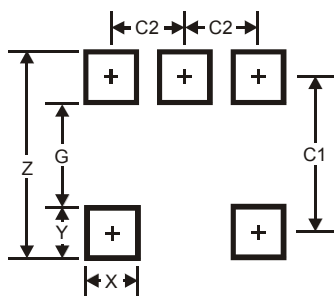


SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT25

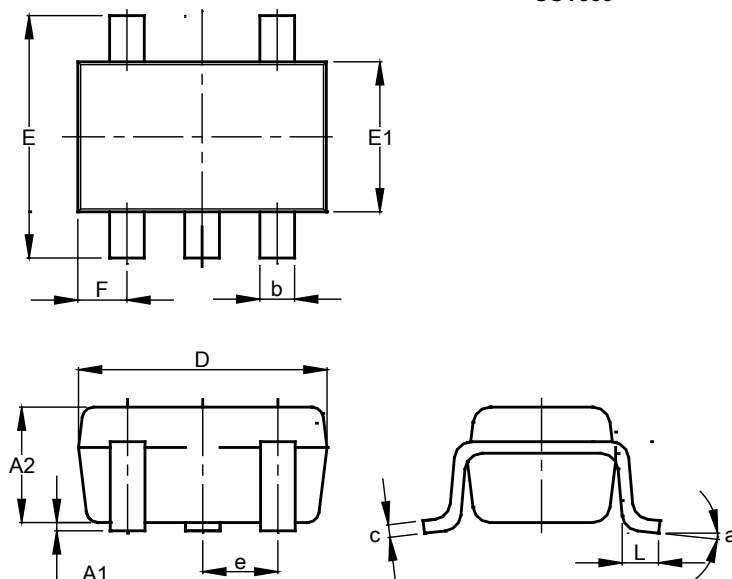


Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT353

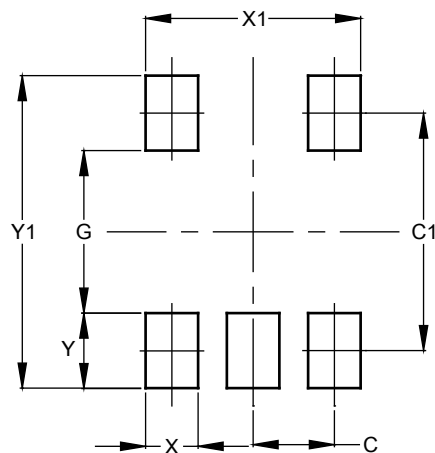


SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT353

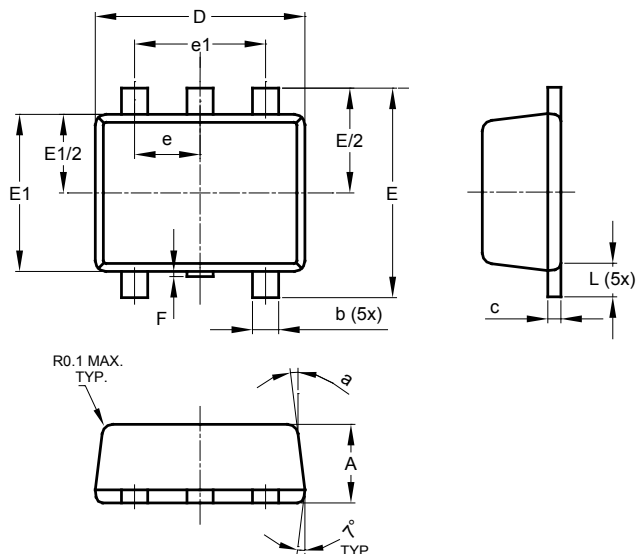


Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT553

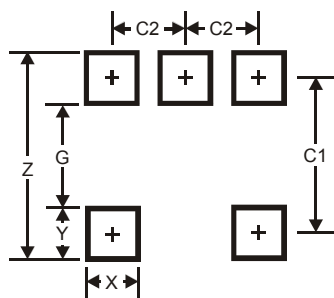


SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
a	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT553

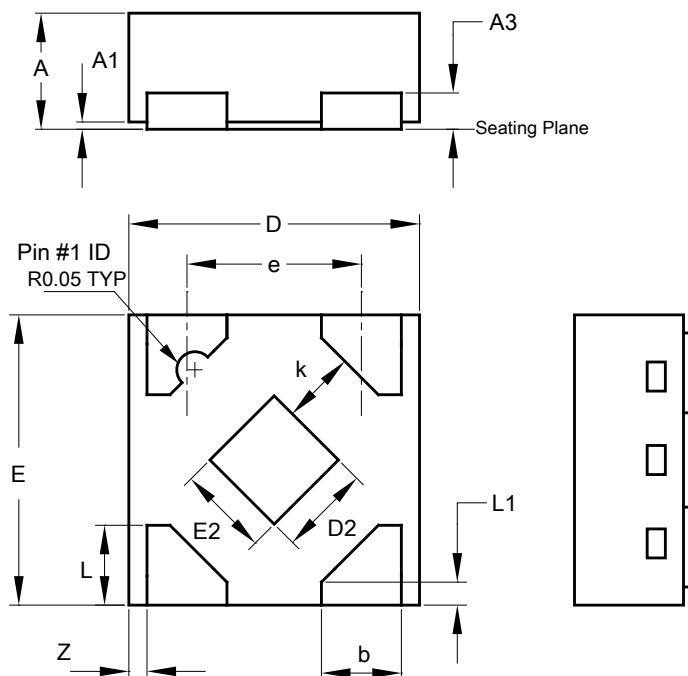


Dimensions	Value
Z	• 2.2
G	• 1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN0808-4

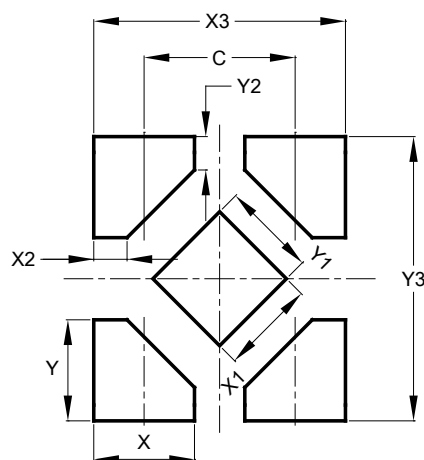


X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN0808-4

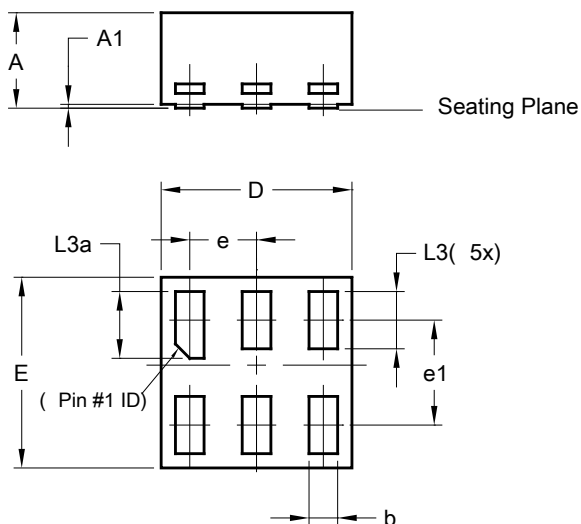


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1010-6 (Type B)

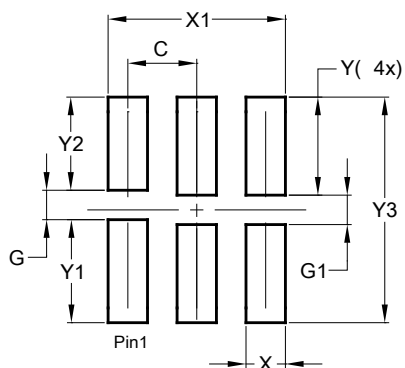


X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1010-6 (Type B)

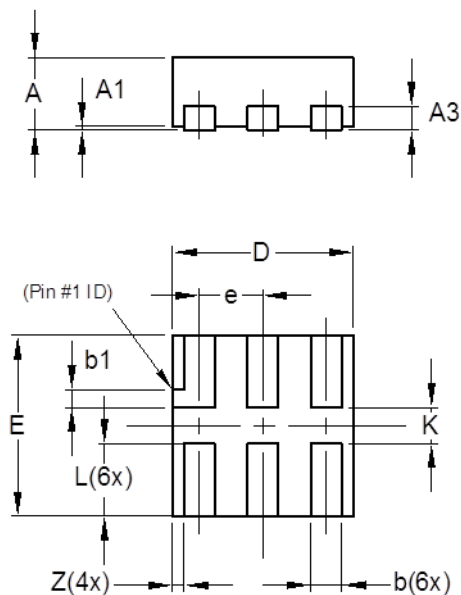


Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6

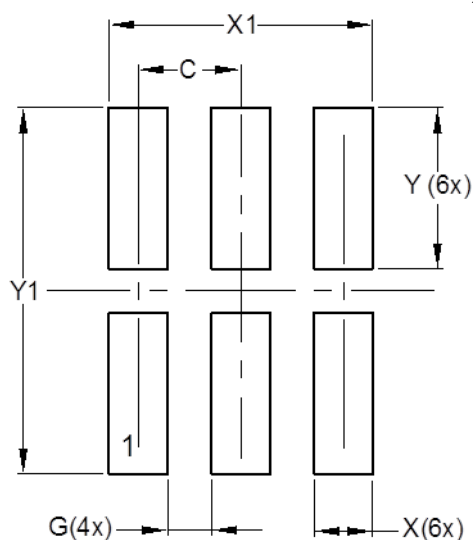


X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6

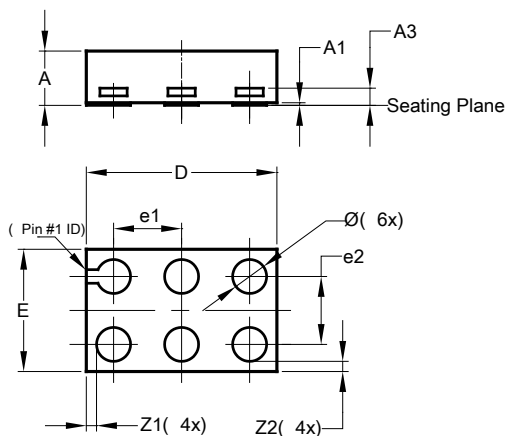


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1409-6

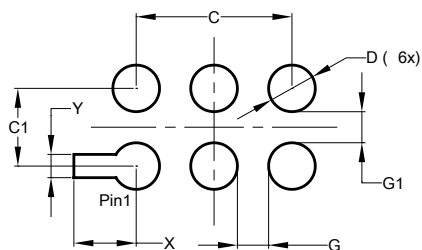


X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1409-6

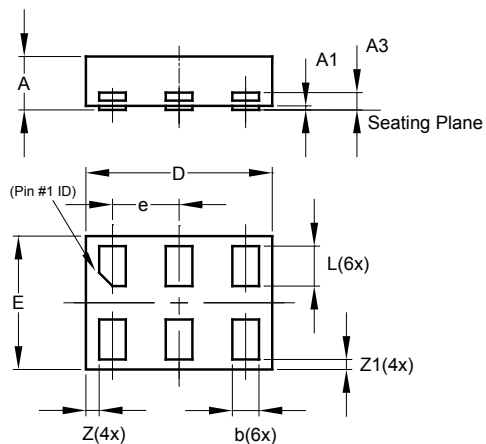


Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6

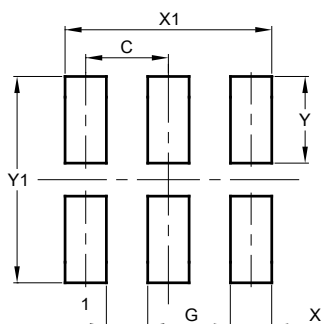


X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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